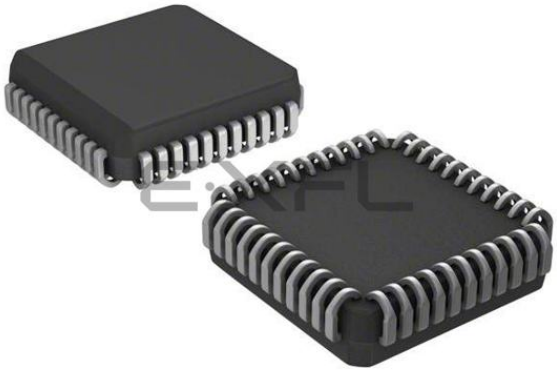


Welcome to E-XFL.COM

What is "Embedded - Microcontrollers"?

"Embedded - Microcontrollers" refer to small, integrated circuits designed to perform specific tasks within larger systems. These microcontrollers are essentially compact computers on a single chip, containing a processor core, memory, and programmable input/output peripherals. They are called "embedded" because they are embedded within electronic devices to control various functions, rather than serving as standalone computers. Microcontrollers are crucial in modern electronics, providing the intelligence and control needed for a wide range of applications.

Applications of "Embedded - Microcontrollers"

Details	
Product Status	Obsolete
Core Processor	80C51
Core Size	8-Bit
Speed	30/20MHz
Connectivity	UART/USART
Peripherals	POR
Number of I/O	32
Program Memory Size	-
Program Memory Type	ROMless
EEPROM Size	-
RAM Size	256 x 8
Voltage - Supply (Vcc/Vdd)	2.7V ~ 5.5V
Data Converters	-
Oscillator Type	Internal
Operating Temperature	-40°C ~ 85°C (TA)
Mounting Type	Surface Mount
Package / Case	44-LCC (J-Lead)
Supplier Device Package	44-PLCC (16.6x16.6)
Purchase URL	https://www.e-xfl.com/product-detail/microchip-technology/ts80c32x2-lib

Mnemonic	Pin Number			Type	Name and Function
	DIL	LCC	VQFP 1.4		
V_{SS}	20	22	16	I	**Ground:** 0V reference
Vss1		1	39	I	Optional Ground: **Contact the Sales Office for ground connection.**
V_{CC}	40	44	38	I	**Power Supply:** This is the power supply voltage for normal, idle and power-down operation
P0.0-P0.7	39-32	43-36	37-30	I/O	**Port 0**: Port 0 is an open-drain, bidirectional I/O port. Port 0 pins that have 1s written to them float and can be used as high impedance inputs.Port 0 pins must be polarized to Vcc or Vss in order to prevent any parasitic current consumption. Port 0 is also the multiplexed low-order address and data bus during access to external program and data memory. In this application, it uses strong internal pull-up when emitting 1s. Port 0 also inputs the code bytes during EPROM programming. External pull-ups are required during program verification during which P0 outputs the code bytes.
P1.0-P1.7	1-8	2-9	40-44 1-3	I/O	Port 1: Port 1 is an 8-bit bidirectional I/O port with internal pull-ups. Port 1 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 1 pins that are externally pulled low will source current because of the internal pull-ups. Port 1 also receives the low-order address byte during memory programming and verification. Alternate functions for Port 1 include:
	1	2	40	I/O	**T2 (P1.0):** Timer/Counter 2 external count input/Clockout
	2	3	41	I	**T2EX (P1.1):** Timer/Counter 2 Reload/Capture/Direction Control
P2.0-P2.7	21-28	24-31	18-25	I/O	**Port 2**: Port 2 is an 8-bit bidirectional I/O port with internal pull-ups. Port 2 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 2 pins that are externally pulled low will source current because of the internal pull-ups. Port 2 emits the high-order address byte during fetches from external program memory and during accesses to external data memory that use 16-bit addresses (MOVX atDPTR).In this application, it uses strong internal pull-ups emitting 1s. During accesses to external data memory that use 8-bit addresses (MOVX atRi), port 2 emits the contents of the P2 SFR. Some Port 2 pins receive the high order address bits during EPROM programming and verification: P2.0 to P2.4
P3.0-P3.7	10-17	11, 13-19	5, 7-13	I/O	Port 3: Port 3 is an 8-bit bidirectional I/O port with internal pull-ups. Port 3 pins that have 1s written to them are pulled high by the internal pull-ups and can be used as inputs. As inputs, Port 3 pins that are externally pulled low will source current because of the internal pull-ups. Port 3 also serves the special features of the 80C51 family, as listed below.
	10	11	5	I	**RXD (P3.0):** Serial input port
	11	13	7	O	**TXD (P3.1):** Serial output port
	12	14	8	I	**$\overline{\text{INT0}}$ (P3.2):** External interrupt 0

Figure 5. Clock-Out Mode C/$\overline{T2}$ = 0

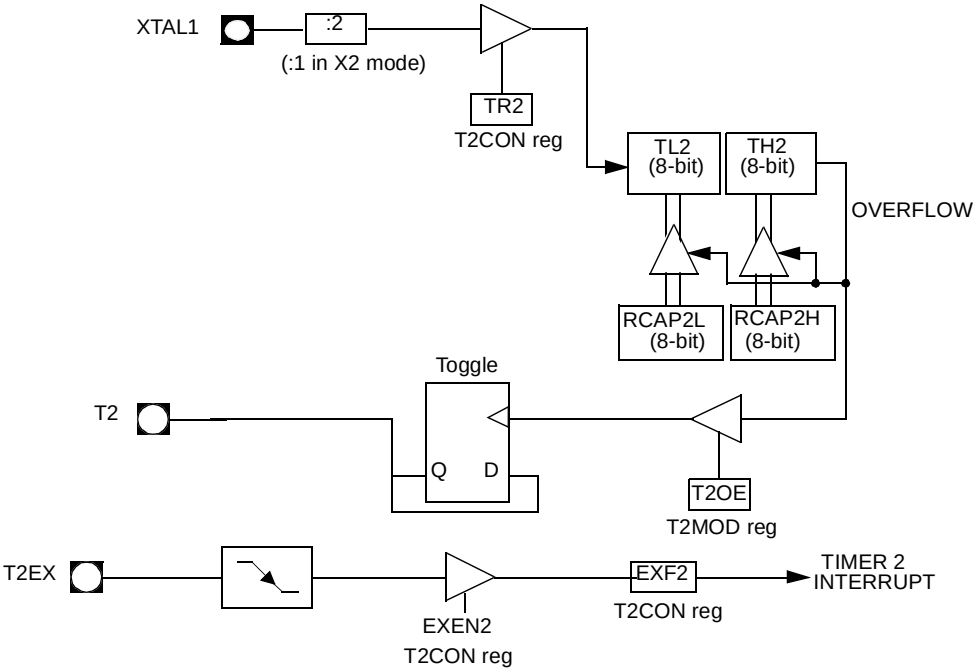


Table 5. T2CON Register

T2CON - Timer 2 Control Register (C8h)

7	6	5	4	3	2	1	0
TF2	**EXF2**	**RCLK**	**TCLK**	**EXEN2**	**TR2**	**C/T2#**	**CP/RL2#**

Bit Number	Bit Mnemonic	Description
7	TF2	**Timer 2 overflow Flag** Must be cleared by software. Set by hardware on timer 2 overflow, if RCLK = 0 and TCLK = 0.
6	EXF2	**Timer 2 External Flag** Set when a capture or a reload is caused by a negative transition on T2EX pin if EXEN2=1. When set, causes the CPU to vector to timer 2 interrupt routine when timer 2 interrupt is enabled. Must be cleared by software. EXF2 doesn't cause an interrupt in Up/down counter mode (DCEN = 1)
5	RCLK	**Receive Clock bit** Clear to use timer 1 overflow as receive clock for serial port in mode 1 or 3. Set to use timer 2 overflow as receive clock for serial port in mode 1 or 3.
4	TCLK	**Transmit Clock bit** Clear to use timer 1 overflow as transmit clock for serial port in mode 1 or 3. Set to use timer 2 overflow as transmit clock for serial port in mode 1 or 3.
3	EXEN2	**Timer 2 External Enable bit** Clear to ignore events on T2EX pin for timer 2 operation. Set to cause a capture or reload when a negative transition on T2EX pin is detected, if timer 2 is not used to clock the serial port.
2	TR2	**Timer 2 Run control bit** Clear to turn off timer 2. Set to turn on timer 2.
1	C/T2#	**Timer/Counter 2 select bit** Clear for timer operation (input from internal clock system: F_{OSC}). Set for counter operation (input from T2 input pin, falling edge trigger). Must be 0 for clock out mode.
0	CP/RL2#	**Timer 2 Capture/Reload bit** If RCLK=1 or TCLK=1, CP/RL2# is ignored and timer is forced to Auto-reload on timer 2 overflow. Clear to Auto-reload on timer 2 overflows or negative transitions on T2EX pin if EXEN2=1. Set to capture on negative transitions on T2EX pin if EXEN2=1.

Reset Value = 0000 0000b

Bit addressable

Table 6. T2MOD Register

T2MOD - Timer 2 Mode Control Register (C9h)

7	6	5	4	3	2	1	0
-	-	-	-	-	-	T2OE	DCEN

Bit Number	Bit Mnemonic	Description
7	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
6	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
3	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
2	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
1	T2OE	**Timer 2 Output Enable bit** Clear to program P1.0/T2 as clock input or I/O port. Set to program P1.0/T2 as clock output.
0	DCEN	**Down Counter Enable bit** Clear to disable timer 2 as up/down counter. Set to enable timer 2 as up/down counter.

Reset Value = XXXX XX00b

Not bit addressable

TS80C52X2 Serial I/O Port

The serial I/O port in the TS80C52X2 is compatible with the serial I/O port in the 80C52. It provides both synchronous and asynchronous communication modes. It operates as an Universal Asynchronous Receiver and Transmitter (UART) in three full-duplex modes (Modes 1, 2 and 3). Asynchronous transmission and reception can occur simultaneously and at different baud rates

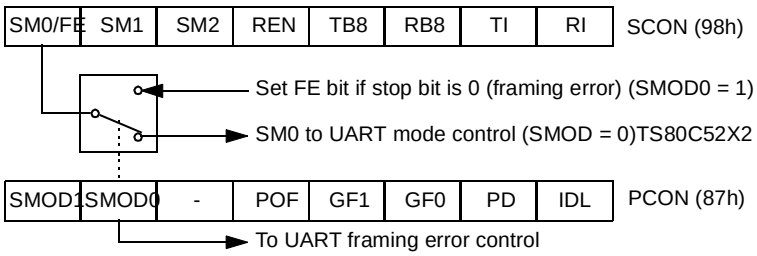
Serial I/O port includes the following enhancements:

- Framing error detection
- Automatic address recognition

Framing Error Detection

Framing bit error detection is provided for the three asynchronous modes (modes 1, 2 and 3). To enable the framing bit error detection feature, set SMOD0 bit in PCON register (See Figure 6).

Figure 6. Framing Error Block Diagram



When this feature is enabled, the receiver checks each incoming data frame for a valid stop bit. An invalid stop bit may result from noise on the serial lines or from simultaneous transmission by two CPUs. If a valid stop bit is not found, the Framing Error bit (FE) in SCON register (See Table 9.) bit is set.
Software may examine FE bit after each reception to check for data errors. Once set, only software or a reset can clear FE bit. Subsequently received frames with valid stop bits cannot clear FE bit. When FE feature is enabled, RI rises on stop bit instead of the last data bit (See Figure 7. and Figure 8.).

Figure 7. UART Timings in Mode 1

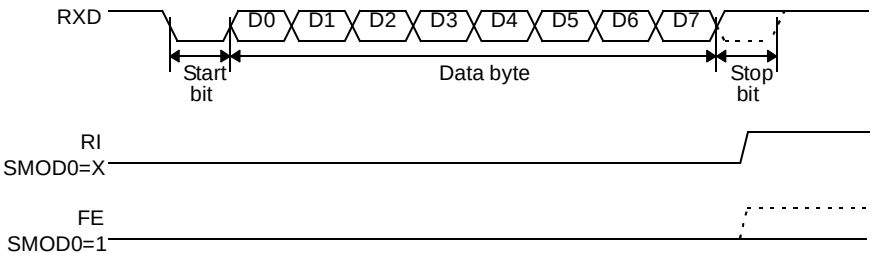
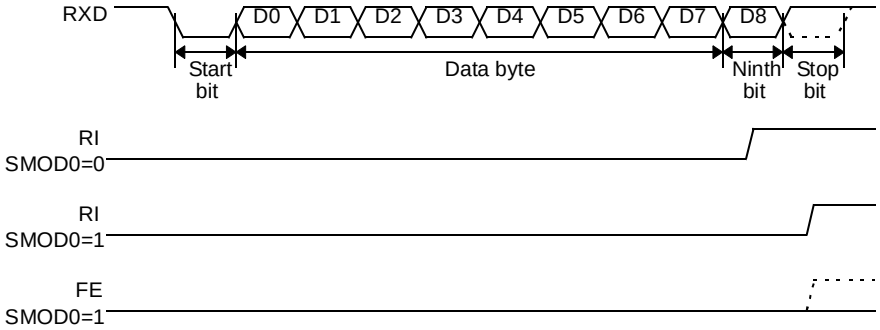


Figure 8. UART Timings in Modes 2 and 3



Automatic Address Recognition

The automatic address recognition feature is enabled when the multiprocessor communication feature is enabled (SM2 bit in SCON register is set).

Implemented in hardware, automatic address recognition enhances the multiprocessor communication feature by allowing the serial port to examine the address of each incoming command frame. Only when the serial port recognizes its own address, the receiver sets RI bit in SCON register to generate an interrupt. This ensures that the CPU is not interrupted by command frames addressed to other devices.

If desired, you may enable the automatic address recognition feature in mode 1. In this configuration, the stop bit takes the place of the ninth data bit. Bit RI is set only when the received command frame address matches the device's address and is terminated by a valid stop bit.

To support automatic address recognition, a device is identified by a given address and a broadcast address.

Note: The multiprocessor communication and automatic address recognition features cannot be enabled in mode 0 (i.e. setting SM2 bit in SCON register in mode 0 has no effect).

Given Address

Each device has an individual address that is specified in SADDR register; the SADEN register is a mask byte that contains don't-care bits (defined by zeros) to form the device's given address. The don't-care bits provide the flexibility to address one or more slaves at a time. The following example illustrates how a given address is formed.

To address a device by its individual address, the SADEN mask byte must be `1111 1111b`.

For example:

```
SADDR0101 0110b
SADEN1111 1100b
Given0101 01XXb
```

The following is an example of how to use given addresses to address different slaves:

```
Slave A:SADDR1111 0001b
    SADEN1111 1010b
    Given1111 0X0Xb


Slave B:SADDR1111 0011b
    SADEN1111 1001b
    Given1111 0XX1b


Slave C:SADDR1111 0010b
    SADEN1111 1101b
    Given1111 00X1b
```

The SADEN byte is selected so that each slave may be addressed separately.

For slave A, bit 0 (the LSB) is a don't-care bit; for slaves B and C, bit 0 is a 1. To communicate with slave A only, the master must send an address where bit 0 is clear (e.g.

Table 10. PCON Register

PCON - Power Control Register (87h)

7	6	5	4	3	2	1	0
SMOD1	**SMOD0**	**-**	**POF**	**GF1**	**GF0**	**PD**	**IDL**

Bit Number	Bit Mnemonic	Description
7	SMOD1	**Serial port Mode bit 1** Set to select double baud rate in mode 1, 2 or 3.
6	SMOD0	**Serial port Mode bit 0** Clear to select SM0 bit in SCON register. Set to to select FE bit in SCON register.
5	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
4	POF	**Power-off Flag** Clear to recognize next reset type. Set by hardware when VCC rises from 0 to its nominal voltage. Can also be set by software.
3	GF1	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
2	GF0	**General purpose Flag** Cleared by user for general purpose usage. Set by user for general purpose usage.
1	PD	**Power-down mode bit** Cleared by hardware when reset occurs. Set to enter power-down mode.
0	IDL	**Idle mode bit** Clear by hardware when interrupt or reset occurs. Set to enter idle mode.

Reset Value = 00X1 0000b
Not bit addressable

Power-off flag reset value will be 1 only after a power on (cold reset). A warm reset doesn't affect the value of this bit.

Table 13. IP Register

IP - Interrupt Priority Register (B8h)

7	6	5	4	3	2	1	0
-	-	PT2	PS	PT1	PX1	PT0	PX0

Bit Number	Bit Mnemonic	Description
7	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
6	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
5	PT2	**Timer 2 overflow interrupt Priority bit** Refer to PT2H for priority level.
4	PS	**Serial port Priority bit** Refer to PSH for priority level.
3	PT1	**Timer 1 overflow interrupt Priority bit** Refer to PT1H for priority level.
2	PX1	**External interrupt 1 Priority bit** Refer to PX1H for priority level.
1	PT0	**Timer 0 overflow interrupt Priority bit** Refer to PT0H for priority level.
0	PX0	**External interrupt 0 Priority bit** Refer to PX0H for priority level.

Reset Value = XX00 0000b

Bit addressable

Table 14. IPH Register

IPH - Interrupt Priority High Register (B7h)

7	6	5	4	3	2	1	0
-	-	PT2H	PSH	PT1H	PX1H	PT0H	PX0H

Bit Number	Bit Mnemonic	Description
7	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
6	-	**Reserved** The value read from this bit is indeterminate. Do not set this bit.
5	PT2H	**Timer 2 overflow interrupt Priority High bit** PT2H PT2 Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
4	PSH	**Serial port Priority High bit** PSH PS Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
3	PT1H	**Timer 1 overflow interrupt Priority High bit** PT1H PT1 Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
2	PX1H	**External interrupt 1 Priority High bit** PX1H PX1 Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
1	PT0H	**Timer 0 overflow interrupt Priority High bit** PT0H PT0 Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest
0	PX0H	**External interrupt 0 Priority High bit** PX0H PX0 Priority Level 0 0 Lowest 0 1 1 0 1 1 Highest

Reset Value = XX00 0000b

Not bit addressable

Idle mode

An instruction that sets PCON.0 causes that to be the last instruction executed before going into the Idle mode. In the Idle mode, the internal clock signal is gated off to the CPU, but not to the interrupt, Timer, and Serial Port functions. The CPU status is preserved in its entirely : the Stack Pointer, Program Counter, Program Status Word, Accumulator and all other registers maintain their data during Idle. The port pins hold the logical states they had at the time Idle was activated. ALE and PSEN hold at logic high levels.

There are two ways to terminate the Idle. Activation of any enabled interrupt will cause PCON.0 to be cleared by hardware, terminating the Idle mode. The interrupt will be serviced, and following RETI the next instruction to be executed will be the one following the instruction that put the device into idle.

The flag bits GF0 and GF1 can be used to give an indication if an interrupt occured during normal operation or during an Idle. For example, an instruction that activates Idle can also set one or both flag bits. When Idle is terminated by an interrupt, the interrupt service routine can examine the flag bits.

The other way of terminating the Idle mode is with a hardware reset. Since the clock oscillator is still running, the hardware reset needs to be held active for only two machine cycles (24 oscillator periods) to complete the reset.

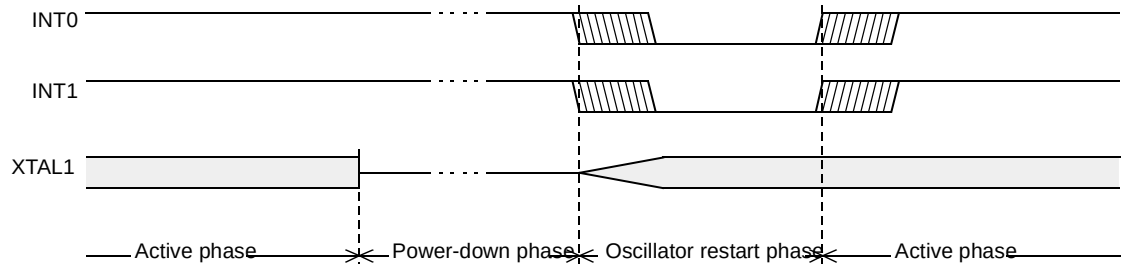
Power-down Mode

To save maximum power, a power-down mode can be invoked by software (Refer to Table 10., PCON register).

In power-down mode, the oscillator is stopped and the instruction that invoked power-down mode is the last instruction executed. The internal RAM and SFRs retain their value until the power-down mode is terminated. V_{CC} can be lowered to save further power. Either a hardware reset or an external interrupt can cause an exit from power-down. To properly terminate power-down, the reset or external interrupt should not be executed before V_{CC} is restored to its normal operating level and must be held active long enough for the oscillator to restart and stabilize.

Only external interrupts $\overline{INT0}$ and $\overline{INT1}$ are useful to exit from power-down. For that, interrupt must be enabled and configured as level or edge sensitive interrupt input.
Holding the pin low restarts the oscillator but bringing the pin high completes the exit as detailed in Figure 10. When both interrupts are enabled, the oscillator restarts as soon as one of the two inputs is held low and power down exit will be completed when the first input will be released. In this case the higher priority interrupt service routine is executed.
Once the interrupt is serviced, the next instruction to be executed after RETI will be the one following the instruction that put TS80C52X2 into power-down mode.

Figure 10. Power-down Exit Waveform



Exit from power-down by reset redefines all the SFRs, exit from power-down by external interrupt does no affect the SFRs.

Exit from power-down by either reset or external interrupt does not affect the internal RAM content.

Note: If idle mode is activated with power-down mode (IDL and PD bits set), the exit sequence is unchanged, when execution is vectored to interrupt, PD and IDL bits are cleared and idle mode is not entered.

Table 15. The State of Ports During Idle and Power-down Modes

Mode	Program Memory	ALE	PSEN	PORT0	PORT1	PORT2	PORT3
Idle	Internal	1	1	Port Data(1)	Port Data	Port Data	Port Data
Idle	External	1	1	Floating	Port Data	Address	Port Data
Power Down	Internal	0	0	Port Data(1)	Port Data	Port Data	Port Data
Power Down	External	0	0	Floating	Port Data	Port Data	Port Data

Note: 1. Port 0 can force a "zero" level. A "one" will leave port floating.

Electrical Characteristics

Absolute Maximum Ratings[1]

Ambiant Temperature Under Bias:
C = commercial.....0°C to 70°C
I = industrial .....-40°C to 85°C
Storage Temperature ..... -65°C to + 150°C
Voltage on V_{CC} to V_{SS}.....-0.5V to + 7 V
Voltage on V_{PP} to V_{SS} .....-0.5V to + 13 V
Voltage on Any Pin to V_{SS}.....-0.5V to V_{CC} + 0.5V
Power Dissipation ..... 1 W[2]

Notes:
1. Stresses at or above those listed under " Absolute Maximum Ratings" may cause permanent damage to the device. This is a stress rating only and functional operation of the device at these or any other conditions above those indicated in the operational sections of this specification is not implied. Exposure to absolute maximum rating conditions may affect device reliability.
2. This value is based on the maximum allowable die temperature and the thermal resistance of the package.

Power Consumption Measurement

Since the introduction of the first C51 devices, every manufacturer made operating Icc measurements under reset, which made sense for the designs were the CPU was running under reset. In Atmel new devices, the CPU is no more active during reset, so the power consumption is very low but is not really representative of what will happen in the customer system. That's why, while keeping measurements under Reset, Atmel presents a new way to measure the operating Icc:

Using an internal test ROM, the following code is executed:

Label: SJMP Label (80 FE)

Ports 1, 2, 3 are disconnected, Port 0 is tied to FFh, EA = Vcc, RST = Vss, XTAL2 is not connected and XTAL1 is driven by the clock.

This is much more representative of the real operating Icc.

DC Parameters for Standard Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 5V ± 10%; F = 0 to 40 MHz.

Table 22. DC Parameters in Standard Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3 [6]			0.3 0.45 1.0	V V V	I_{OL} = 100 µA[4] I_{OL} = 1.6 mA[4] I_{OL} = 3.5 mA[4]
V_{OL1}	Output Low Voltage, port 0 [6]			0.3 0.45 1.0	V V V	I_{OL} = 200 µA[4] I_{OL} = 3.2 mA[4] I_{OL} = 7.0 mA[4]
V_{OL2}	Output Low Voltage, ALE, $\overline{PSEN}$			0.3 0.45 1.0	V V V	I_{OL} = 100 µA[4] I_{OL} = 1.6 mA[4] I_{OL} = 3.5 mA[4]

Table 22. DC Parameters in Standard Voltage (Continued)

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{OH}	Output High Voltage, ports 1, 2, 3	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -10 µA I_{OH} = -30 µA I_{OH} = -60 µA V_{CC} = 5V ± 10%
V_{OH1}	Output High Voltage, port 0	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -200 µA I_{OH} = -3.2 mA I_{OH} = -7.0 mA V_{CC} = 5V ± 10%
V_{OH2}	Output High Voltage,ALE, $\overline{PSEN}$	V_{CC} - 0.3 V_{CC} - 0.7 V_{CC} - 1.5			V V V	I_{OH} = -100 µA I_{OH} = -1.6 mA I_{OH} = -3.5 mA V_{CC} = 5V ± 10%
R_{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
I_{IL}	Logical 0 Input Current ports 1, 2 and 3			-50	µA	Vin = 0.45V
I_{LI}	Input Leakage Current			±10	µA	0.45V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3			-650	µA	Vin = 2.0 V
C_{IO}	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz T_A = 25°C
I_{PD}	Power Down Current		20 (5)	50	µA	2.0 V < V_{CC} < 5.5V(3)
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.4 Freq (MHz) at12MHz 5.8 at16MHz 7.4	mA	V_{CC} = 5.5V(1)
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			3 + 0.6 Freq (MHz) at12MHz 10.2 at16MHz 12.6	mA	V_{CC} = 5.5V(8)
I_{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.25+0.3 Freq (MHz) at12MHz 3.9 at16MHz 5.1	mA	V_{CC} = 5.5V(2)

DC Parameters for Low Voltage

T_A = 0°C to +70°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5V ; F = 0 to 30 MHz.
T_A = -40°C to +85°C; V_{SS} = 0 V; V_{CC} = 2.7 V to 5.5V ; F = 0 to 30 MHz.

Table 23. DC Parameters for Low Voltage

Symbol	Parameter	Min	Typ	Max	Unit	Test Conditions
V_{IL}	Input Low Voltage	-0.5		0.2 V_{CC} - 0.1	V	
V_{IH}	Input High Voltage except XTAL1, RST	0.2 V_{CC} + 0.9		V_{CC} + 0.5	V	
V_{IH1}	Input High Voltage, XTAL1, RST	0.7 V_{CC}		V_{CC} + 0.5	V	
V_{OL}	Output Low Voltage, ports 1, 2, 3 (6)			0.45	V	I_{OL} = 0.8 mA(4)
V_{OL1}	Output Low Voltage, port 0, ALE, $\overline{PSEN}$ (6)			0.45	V	I_{OL} = 1.6 mA(4)
V_{OH}	Output High Voltage, ports 1, 2, 3	0.9 V_{CC}			V	I_{OH} = -10 µA
V_{OH1}	Output High Voltage, port 0, ALE, $\overline{PSEN}$	0.9 V_{CC}			V	I_{OH} = -40 µA
I_{IL}	Logical 0 Input Current ports 1, 2 and 3			-50	µA	Vin = 0.45V
I_{LI}	Input Leakage Current			±10	µA	0.45V < Vin < V_{CC}
I_{TL}	Logical 1 to 0 Transition Current, ports 1, 2, 3			-650	µA	Vin = 2.0 V
R_{RST}	RST Pulldown Resistor	50	90 (5)	200	kΩ	
CIO	Capacitance of I/O Buffer			10	pF	Fc = 1 MHz T_A = 25°C
I_{PD}	Power Down Current		20 (5) 10 (5)	50 30	µA	V_{CC} = 2.0 V to 5.5V(3) V_{CC} = 2.0 V to 3.3 V(3)
I_{CC} under RESET	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.2 Freq (MHz) at12MHz 3.4 at16MHz 4.2	mA	V_{CC} = 3.3 V(1)
I_{CC} operating	Power Supply Current Maximum values, X1 mode: (7)			1 + 0.3 Freq (MHz) at12MHz 4.6 at16MHz 5.8	mA	V_{CC} = 3.3 V(8)
I_{CC} idle	Power Supply Current Maximum values, X1 mode: (7)			0.15 Freq (MHz) + 0.2 at12MHz 2 at16MHz 2.6	mA	V_{CC} = 3.3 V(2)

Notes:
1. I_{CC} under reset is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns (see Figure 17.), V_{IL} = V_{SS} + 0.5V,
   V_{IH} = V_{CC} - 0.5V; XTAL2 N.C.; $\overline{EA}$ = RST = Port 0 = V_{CC}. I_{CC} would be slightly higher if a crystal oscillator used..
2. Idle I_{CC} is measured with all output pins disconnected; XTAL1 driven with T_{CLCH}, T_{CHCL} = 5 ns, V_{IL} = V_{SS} + 0.5V, V_{IH} = V_{CC} - 0.5V; XTAL2 N.C; Port 0 = V_{CC}; $\overline{EA}$ = RST = V_{SS} (see Figure 15.).
3. Power Down I_{CC} is measured with all output pins disconnected; $\overline{EA}$ = V_{SS}, PORT 0 = V_{CC}; XTAL2 NC.; RST = V_{SS} (see Figure 16.).
4. Capacitance loading on Ports 0 and 2 may cause spurious noise pulses to be superimposed on the V_{OL}s of ALE and Ports 1 and 3. The noise is due to external bus capacitance discharging into the Port 0 and Port 2 pins when these pins make 1 to 0 transitions during bus operation. In the worst cases (capacitive loading 100pF), the noise pulse on the ALE line may exceed 0.45V with maxi V_{OL} peak 0.6V. A Schmitt Trigger use is not necessary.
5. Typicals are based on a limited number of samples and are not guaranteed. The values listed are at room temperature and 5V.
6. Under steady state (non-transient) conditions, I_{OL} must be externally limited as follows:
   Maximum I_{OL} per port pin: 10 mA
   Maximum I_{OL} per 8-bit port:

Table 28., Table 31. and Table 34. give the frequency derating formula of the AC parameter. To calculate each AC symbols, take the x value corresponding to the speed grade you need (-M, -V or -L) and replace this value in the formula. Values of the frequency must be limited to the corresponding speed grade:

Table 25. Max frequency for derating formula regarding the speed grade

	-M X1 mode	-M X2 mode	-V X1 mode	-V X2 mode	-L X1 mode	-L X2 mode
Freq (MHz)	40	20	40	30	30	20
T (ns)	25	50	25	33.3	33.3	50

Example:

T_{LLIV} in X2 mode for a -V part at 20 MHz (T = $1/20^{E6}$ = 50 ns):

x= 22 (Table 28.)

T= 50ns

T_{LLIV}= 2T - x = 2 x 50 - 22 = 78ns

External Program Memory Characteristics

Table 26. Symbol Description

Symbol	Parameter
T	Oscillator clock period
T_{LHLL}	ALE pulse width
T_{AVLL}	Address Valid to ALE
T_{LLAX}	Address Hold After ALE
T_{LLIV}	ALE to Valid Instruction In
T_{LLPL}	ALE to $\overline{PSEN}$
T_{PLPH}	$\overline{PSEN}$ Pulse Width
T_{PLIV}	$\overline{PSEN}$ to Valid Instruction In
T_{PXIX}	Input Instruction Hold After $\overline{PSEN}$
T_{PXIZ}	Input Instruction FloatAfter $\overline{PSEN}$
T_{PXAV}	$\overline{PSEN}$ to Address Valid
T_{AVIV}	Address to Valid Instruction In
T_{PLAZ}	$\overline{PSEN}$ Low to Address Float

Table 27. AC Parameters for Fix Clock

Speed	-M 40 MHz		-V X2 mode 30 MHz 60 MHz equiv.		-V standard mode 40 MHz		-L X2 mode 20 MHz 40 MHz equiv.		-L standard mode 30 MHz		Units
Symbol	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	
T	25		33		25		50		33		ns
T_{LHLL}	40		25		42		35		52		ns
T_{AVLL}	10		4		12		5		13		ns
T_{LLAX}	10		4		12		5		13		ns
T_{LLIV}		70		45		78		65		98	ns
T_{LLPL}	15		9		17		10		18		ns
T_{PLPH}	55		35		60		50		75		ns
T_{PLIV}		35		25		50		30		55	ns
T_{PXIX}	0		0		0		0		0		ns
T_{PXIZ}		18		12		20		10		18	ns
T_{AVIV}		85		53		95		80		122	ns
T_{PLAZ}		10		10		10		10		10	ns

Table 28. AC Parameters for a Variable Clock: derating formula

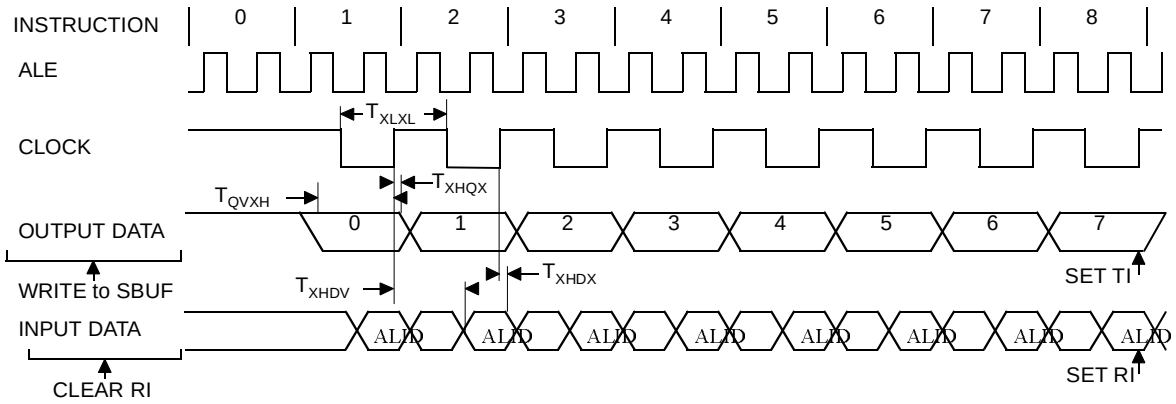
Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{LHLL}	Min	2 T - x	T - x	10	8	15	ns
T_{AVLL}	Min	T - x	0.5 T - x	15	13	20	ns
T_{LLAX}	Min	T - x	0.5 T - x	15	13	20	ns
T_{LLIV}	Max	4 T - x	2 T - x	30	22	35	ns
T_{LLPL}	Min	T - x	0.5 T - x	10	8	15	ns
T_{PLPH}	Min	3 T - x	1.5 T - x	20	15	25	ns
T_{PLIV}	Max	3 T - x	1.5 T - x	40	25	45	ns
T_{PXIX}	Min	x	x	0	0	0	ns
T_{PXIZ}	Max	T - x	0.5 T - x	7	5	15	ns
T_{AVIV}	Max	5 T - x	2.5 T - x	40	30	45	ns
T_{PLAZ}	Max	x	x	10	10	10	ns

Table 34. AC Parameters for a Variable Clock: Derating Formula

Symbol	Type	Standard Clock	X2 Clock	-M	-V	-L	Units
T_{XLXL}	Min	12 T	6 T				ns
T_{QVHX}	Min	10 T - x	5 T - x	50	50	50	ns
T_{XHQX}	Min	2 T - x	T - x	20	20	20	ns
T_{XHDX}	Min	x	x	0	0	0	ns
T_{XHDV}	Max	10 T - x	5 T- x	133	133	133	ns

Shift Register Timing Waveforms

Figure 21. Shift Register Timing Waveforms



Ordering Information

Table 37. Possible Ordering Entries

Part Number[3]	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
TS80C32X2-MCA	ROMLess	5V ±10%	Commercial	40 MHz[1]	PDIL40	Stick
TS80C32X2-MCB	ROMLess	5V ±10%	Commercial	40 MHz[1]	PLCC44	Stick
TS80C32X2-MCC	ROMLess	5V ±10%	Commercial	40 MHz[1]	PQFP44	Tray
TS80C32X2-MCE	ROMLess	5V ±10%	Commercial	40 MHz[1]	VQFP44	Tray
TS80C32X2-LCA	ROMLess	2.7 to 5.5V	Commercial	30 MHz[1]	PDIL40	Stick
TS80C32X2-LCB	ROMLess	2.7 to 5.5V	Commercial	30 MHz[1]	PLCC44	Stick
TS80C32X2-LCC	ROMLess	2.7 to 5.5V	Commercial	30 MHz[1]	PQFP44	Tray
TS80C32X2-LCE	ROMLess	2.7 to 5.5V	Commercial	30 MHz[1]	VQFP44	Tray
TS80C32X2-VCA	ROMLess	5V ±10%	Commercial	60 MHz[3]	PDIL40	Stick
TS80C32X2-VCB	ROMLess	5V ±10%	Commercial	60 MHz[3]	PLCC44	Stick
TS80C32X2-VCC	ROMLess	5V ±10%	Commercial	60 MHz[3]	PQFP44	Tray
TS80C32X2-VCE	ROMLess	5V ±10%	Commercial	60 MHz[3]	VQFP44	Tray
TS80C32X2-MIA	ROMLess	5V ±10%	Industrial	40 MHz[1]	PDIL40	Stick
TS80C32X2-MIB	ROMLess	5V ±10%	Industrial	40 MHz[1]	PLCC44	Stick
TS80C32X2-MIC	ROMLess	5V ±10%	Industrial	40 MHz[1]	PQFP44	Tray
TS80C32X2-MIE	ROMLess	5V ±10%	Industrial	40 MHz[1]	VQFP44	Tray
TS80C32X2-LIA	ROMLess	2.7 to 5.5V	Industrial	30 MHz[1]	PDIL40	Stick
TS80C32X2-LIB	ROMLess	2.7 to 5.5V	Industrial	30 MHz[1]	PLCC44	Stick
TS80C32X2-LIC	ROMLess	2.7 to 5.5V	Industrial	30 MHz[1]	PQFP44	Tray
TS80C32X2-LIE	ROMLess	2.7 to 5.5V	Industrial	30 MHz[1]	VQFP44	Tray
TS80C32X2-VIA	ROMLess	5V ±10%	Industrial	60 MHz[3]	PDIL40	Stick
TS80C32X2-VIB	ROMLess	5V ±10%	Industrial	60 MHz[3]	PLCC44	Stick
TS80C32X2-VIC	ROMLess	5V ±10%	Industrial	60 MHz[3]	PQFP44	Tray
TS80C32X2-VIE	ROMLess	5V ±10%	Industrial	60 MHz[3]	VQFP44	Tray
AT80C32X2-3CSUM	ROMLess	5V ±10%	Industrial & Green	40 MHz[1]	PDIL40	Stick
AT80C32X2-SLSUM	ROMLess	5V ±10%	Industrial & Green	40 MHz[1]	PLCC44	Stick
AT80C32X2-RLTUM	ROMLess	5V ±10%	Industrial & Green	40 MHz[1]	VQFP44	Tray
AT80C32X2-RLTUM	ROMLess	5V ±10%	Industrial & Green	40 MHz[1]	VQFP44	Tape & Reel
AT80C32X2-3CSUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz[1]	PDIL40	Stick
AT80C32X2-SLSUL	ROMLess	2.7 to 5.5V	Industrial & Green	30 MHz[1]	PLCC44	Stick

Table 37. Possible Ordering Entries (Continued)

Part Number[3]	Memory Size	Supply Voltage	Temperature Range	Max Frequency	Package	Packing
AT87C52X2-3CSUM	8K OTP	5V ±10%	Industrial & Green	40 MHz[1]	PDIL40	Stick
AT87C52X2-SLSUM	8K OTP	5V ±10%	Industrial & Green	40 MHz[1]	PLCC44	Stick
AT87C52X2-RLTUM	8K OTP	5V ±10%	Industrial & Green	40 MHz[1]	VQFP44	Tray
AT87C52X2-3CSUL	8K OTP	2.7 to 5.5V	Industrial & Green	30 MHz[1]	PDIL40	Stick
AT87C52X2-SLSUL	8K OTP	2.7 to 5.5V	Industrial & Green	30 MHz[1]	PLCC44	Stick
AT87C52X2-RLTUL	8K OTP	2.7 to 5.5V	Industrial & Green	30 MHz[1]	VQFP44	Tray
AT87C52X2-3CSUV	8K OTP	5V ±10%	Industrial & Green	60 MHz[3]	PDIL40	Stick
AT87C52X2-SLSUV	8K OTP	5V ±10%	Industrial & Green	60 MHz[3]	PLCC44	Stick
AT87C52X2-RLTUV	8K OTP	5V ±10%	Industrial & Green	60 MHz[3]	VQFP44	Tray

Notes: 1. 20 MHz in X2 Mode.
2. Tape and Reel available for SL, PQFP and RL packages
3. 30 MHz in X2 Mode.

Atmel Headquarters

Corporate Headquarters
2325 Orchard Parkway
San Jose, CA 95131
TEL 1(408) 441-0311
FAX 1(408) 487-2600

Europe
Atmel Sarl
Route des Arsenaux 41
Case Postale 80
CH-1705 Fribourg
Switzerland
TEL (41) 26-426-5555
FAX (41) 26-426-5500

Asia
Room 1219
Chinachem Golden Plaza
77 Mody Road Tsimhatsui
East Kowloon
Hong Kong
TEL (852) 2721-9778
FAX (852) 2722-1369

Japan
9F, Tonetsu Shinkawa Bldg.
1-24-8 Shinkawa
Chuo-ku, Tokyo 104-0033
Japan
TEL (81) 3-3523-3551
FAX (81) 3-3523-7581

Atmel Operations

Memory
2325 Orchard Parkway
San Jose, CA 95131
TEL 1(408) 441-0311
FAX 1(408) 436-4314

Microcontrollers
2325 Orchard Parkway
San Jose, CA 95131
TEL 1(408) 441-0311
FAX 1(408) 436-4314

La Chantrerie
BP 70602
44306 Nantes Cedex 3, France
TEL (33) 2-40-18-18-18
FAX (33) 2-40-18-19-60

ASIC/ASSP/Smart Cards
Zone Industrielle
13106 Rousset Cedex, France
TEL (33) 4-42-53-60-00
FAX (33) 4-42-53-60-01

1150 East Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906
TEL 1(719) 576-3300
FAX 1(719) 540-1759

Scottish Enterprise Technology Park
Maxwell Building
East Kilbride G75 0QR, Scotland
TEL (44) 1355-803-000
FAX (44) 1355-242-743

RF/Automotive
Theresienstrasse 2
Postfach 3535
74025 Heilbronn, Germany
TEL (49) 71-31-67-0
FAX (49) 71-31-67-2340

1150 East Cheyenne Mtn. Blvd.
Colorado Springs, CO 80906
TEL 1(719) 576-3300
FAX 1(719) 540-1759

Biometrics/Imaging/Hi-Rel MPU/ High Speed Converters/RF Datacom
Avenue de Rochepleine
BP 123
38521 Saint-Egreve Cedex, France
TEL (33) 4-76-58-30-00
FAX (33) 4-76-58-34-80

---

e-mail
literature@atmel.com

Web Site
http://www.atmel.com

4184G–8051–09/06 /xM